SCBS026C - NOVEMBER 1988 - REVISED APRIL 1994

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- 3-State True Outputs
- Back-to-Back Registers for Storage
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline Packages (DW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (JT, NT)

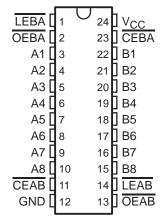
description

The 'BCT543 octal transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (\overline{LEAB} or \overline{LEBA}) and output-enable (\overline{OEAB} or \overline{OEBA}) inputs are provided for each register to permit independent control in either direction of data flow.

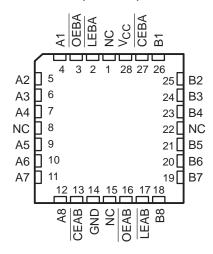
The A-to-B enable (CEAB) input must be low in order to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

The SN54BCT543 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT543 is characterized for operation from 0°C to 70°C.

SN54BCT543...JT OR W PACKAGE SN74BCT543...DW OR NT PACKAGE (TOP VIEW)



SN54BCT543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

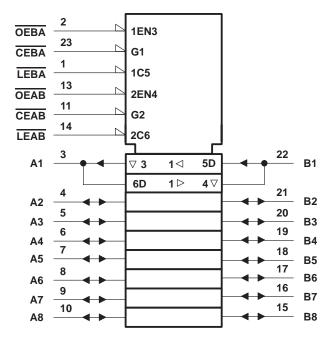
FUNCTION TABLE†

	OUTPUT			
CEAB	LEAB	OEAB	Α	В
Н	Χ	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

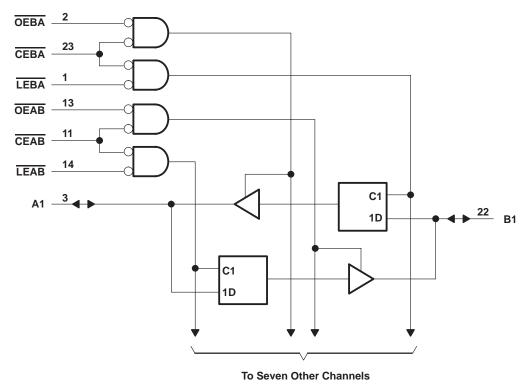
[‡]Output level before the indicated steady-state input conditions were established.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.



SN54BCT543, SN74BCT543 OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS026C - NOVEMBER 1988 - REVISED APRIL 1994

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		– 0.5 V to 7 V
Input voltage range: Control inputs (see	e Note 1)	– 0.5 V to 7 V
	e 1) [´]	
Voltage range applied to any output in t	the disabled or power-off state, VO	– 0.5 V to 7 V
Voltage range applied to any output in t		
Input clamp current, I _{IK}		
Current into any output in the low state:	: SN54BCT543	96 mA
•	SN74BCT543	128 mA
Operating free-air temperature range:	SN54BCT543	– 55°C to 125°C
	SN74BCT543	0°C to 70°C
Storage temperature range		– 65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		SN54BCT543			SN			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			8.0			0.8	V
ΙΙΚ	Input clamp current			-18			-18	mA
lOH	High-level output current			-12			-15	mA
lOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

SN54BCT543, **SN74BCT543 OCTAL REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCBS026C - NOVEMBER 1988 - REVISED APRIL 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEGT COMPITIONS			43	SN			
		TEST CONDITIONS			MIN TYPT		MIN	TYP [†]	MAX	UNIT
٧IK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
			$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		
∨он		V _C C = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					V
			$I_{OH} = -15 \text{ mA}$				2	3.1		
V _{OL}		\/aa	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V
		V _{CC} = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.42	0.55	V
lį		V _{CC} = 5.5 V,	V _I = 5.5 V			0.4			0.4	mA
. +	A or B port	.,	V 07V			70			70	
I _{IH} ‡	Control input	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
. +	A or B port	.,	V 05V			-0.65			-0.65	1
I _{IL} ‡	Control input	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			-0.6			-0.6	mA
IOS§		V _{CC} = 5.5 V,	VO = 0	-100		-225	-100		-225	mA
ICCL	A or B port	V _{CC} = 5.5 V			45	71		45	71	mA
ICCH	A or B port	V _{CC} = 5.5 V			5	8		5	8	mA
ICCZ	A or B port	V _{CC} = 5.5 V			9	15		9	15	mA
Ci	Control input	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		6			6		pF
C _{io}	A or B port	V _{CC} = 5 V,	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$		16			16	·	pF

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				$V_{CC} = 5 \text{ V},$ $T_A = 25^{\circ}\text{C}$		CT543	SN74B	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LEAB or LEBA low		7		8		7		ns
t _{su}	Setup time, data before LEAB or LEBA↑	High or low	4.5		5.5		4.5		ns
t _h	Hold time, data after LEAB or LEBA↑	High or low	1.5		1.5		1.5		ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)				V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω , R2 = 500 Ω , T_A = MIN to MAX \dagger				UNIT
			′1	3CT543		SN54BCT543		SN74BCT543		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A = :: D	D on A	2	5.7	7.5	2	9.9	2	8.8	ns
t _{PHL}	A or B	B or A	2	6.3	8.2	2	9.7	2	9.6	
^t PLH	Ē	A B	2	8.2	10.3	2	13.9	2	12.9	ns
t _{PHL}	LE	A or B	2	8.5	10.6	2	13.2	2	12.7	
^t PZH	ŌĒ		1	6.8	8.6	1	11.4	1	10.7	
^t PZL	OE	A or B	1	8.7	10.8	1	12.8	1	12.3	ns
^t PHZ	ŌĒ		1	5.5	7.2	1	8.8	1	8.1	
t _{PLZ}	OE	A or B	1	4.7	6.4	1	8.1	1	7.2	ns
^t PZH	CE	A - : : D	1	7.6	9.8	1	12.8	1	12	
^t PZL	CE	A or B	1	9.5	11.6	1	13.8	1	13.5	ns
t _{PHZ}	<u>~</u>	A or B	1	5.8	7.5	1	9.3	1	8.5	20
t _{PLZ}	CE		1	4.8	6.7	1	8.4	1	7.6	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



www.ti.com

11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9087001M3A	Active	Production	LCCC (FK) 28	42 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9087001M3A SNJ54BCT 543FK
SN74BCT543DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT543
SN74BCT543DW.A	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT543
SNJ54BCT543FK	Active	Production	LCCC (FK) 28	42 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9087001M3A SNJ54BCT 543FK
SNJ54BCT543FK.A	Active	Production	LCCC (FK) 28	42 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9087001M3A SNJ54BCT 543FK
SNJ54BCT543JT	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9087001ML A SNJ54BCT543JT
SNJ54BCT543JT.A	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9087001ML A SNJ54BCT543JT

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54BCT543, SN74BCT543:

Catalog: SN74BCT543

Military: SN54BCT543

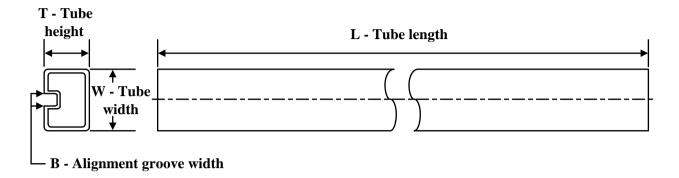
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



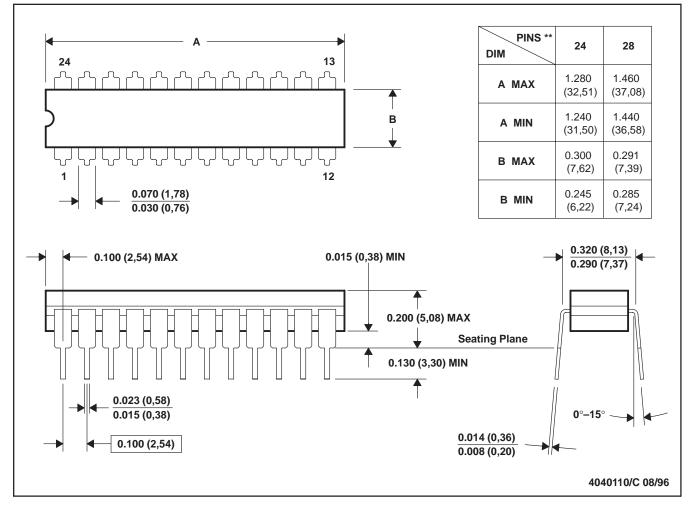
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74BCT543DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74BCT543DW.A	DW	SOIC	24	25	506.98	12.7	4826	6.6

JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE



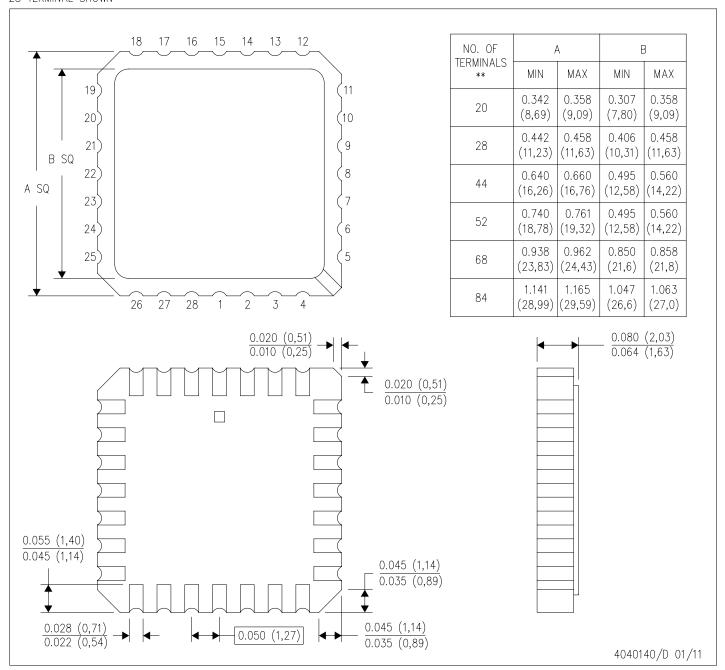
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



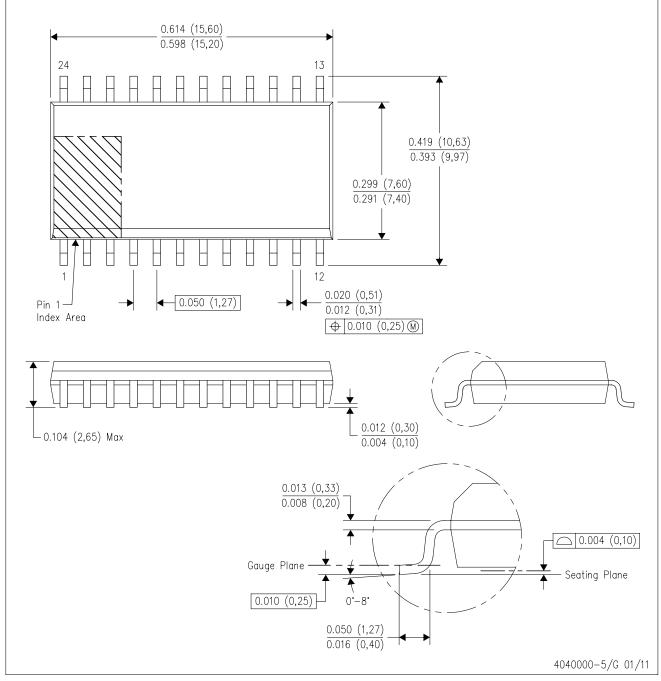
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025